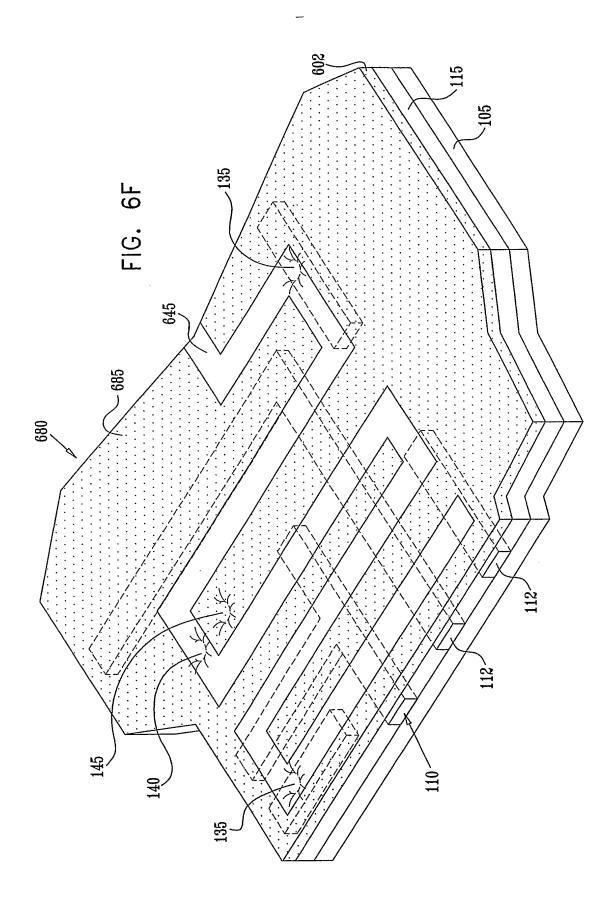
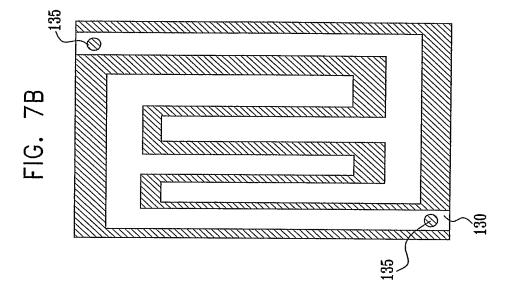


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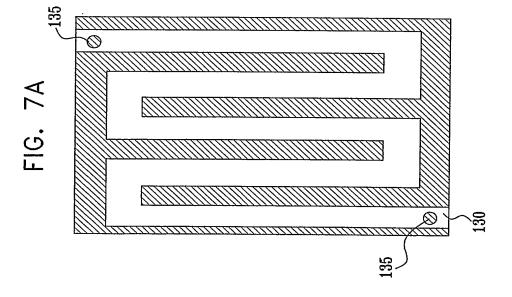


FIG. 8

PROVIDE AN INTEGRATED CIRCUIT (IC) HAVING AN INTERCONNECT LAYER

DEPOSIT, OVER SUBSTANTIALLY ALL OF AN EXPOSED SURFACE OF THE IC, AN ADDITIONAL LAYER OF MATERIAL WHOSE CONDUCTIVITY CAN BE ALTERED

SELECTIVELY ALTER THE CONDUCTIVITY OF A FIRST PORTION OF THE ADDITIONAL LAYER BY SELECTIVE ANNEALING, TO PRODUCE, IN THE ADDITIONAL LAYER, A SUB-CIRCUIT IN OPERATIVE ELECTRICAL COMMUNICATION WITH THE IC

FIG. 9

PROVIDE A PLURALITY OF INTEGRATED CIRCUITS (ICS), EACH HAVING AN INTERCONNECT LAYER

FOR EACH ONE OF THE PLURALITY OF ICS:

DEPOSIT, OVER SUBSTANTIALLY ALL OF AN EXPOSED SURFACE OF THE ONE IC, AN ADDITIONAL LAYER OF MATERIAL WHOSE CONDUCTIVITY CAN BE ALTERED

SELECTIVELY ALTER THE CONDUCTIVITY
OF A FIRST PORTION OF THE ADDITIONAL
LAYER BY SELECTIVE ANNEALING, TO
PRODUCE A

SUB-CIRCUIT IN THE ADDITIONAL LAYER, THE SUB-CIRCUIT
BEING IN OPERATIVE ELECTRICAL
COMMUNICATION WITH THE IC, THE
FIRST PORTION HAVING A DIFFERENT
SHAPE IN SOME OF THE ICS THAN IN OTHER ICS

FIG. 10

PROVIDE AN INTEGRATED CIRCUIT HAVING AN INTERCONNECT LAYER

DEPOSIT, OVER SUBSTANTIALLY ALL OF AN EXPOSED SURFACE OF THE INTEGRATED CIRCUIT, AN ADDITIONAL LAYER OF MATERIAL WHOSE CONDUCTIVITY CAN BE ALTERED

SELECTIVELY DOPE ONLY A FIRST PORTION OF THE ADDITIONAL LAYER OF MATERIAL

SELECTIVELY ALTER THE CONDUCTIVITY OF THE FIRST PORTION OF THE ADDITIONAL LAYER BY ANNEALING, TO PRODUCE A SUB-CIRCUIT IN THE ADDITIONAL LAYER, THE SUB-CIRCUIT BEING IN OPERATIVE ELECTRICAL COMMUNICATION WITH THE INTEGRATED CIRCUIT

FIG. 11

PROVIDE A PLURALITY OF INTEGRATED CIRCUITS (ICS), EACH HAVING AN INTERCONNECT LAYER

DEPOSIT, OVER SUBSTANTIALLY ALL OF AN EXPOSED SURFACE OF EACH OF THE PLURALITY OF INTEGRATED CIRCUITS, AN ADDITIONAL LAYER OF MATERIAL WHOSE CONDUCTIVITY CAN BE ALTERED

FOR EACH ONE OF THE PLURALITY OF INTEGRATED CIRCUITS:

SELECTIVELY DOPE ONLY A FIRST PORTION OF THE ADDITIONAL LAYER OF MATERIAL OF THE ONE INTEGRATED CIRCUIT, THE FIRST PORTION HAVING A DIFFERENT SHAPE IN SOME OF THE ICS THAN IN OTHER ICS

SELECTIVELY ALTER THE CONDUCTIVITY
OF THE FIRST PORTION OF THE
ADDITIONAL LAYER OF EACH OF THE
PLURALITY OF INTEGRATED CIRCUITS
BY ANNEALING, TO PRODUCE A
SUB-CIRCUIT IN THE ADDITIONAL
LAYER, THE SUB-CIRCUIT BEING IN
OPERATIVE ELECTRICAL COMMUNICATION
WITH THE INTEGRATED CIRCUIT